

ADD-A-PAK Generation VII Power Modules Thyristor/Diode and Thyristor/Thyristor, 95 A



ADD-A-PAK

FEATURES

- High voltage
- Industrial standard package
- UL pending
- 3500 V_{RMS} isolating voltage
- Low thermal resistance
- Totally lead (Pb)-free
- Designed and qualified for industrial level



RoHS
COMPLIANT

PRODUCT SUMMARY

$I_{T(AV)}$ or $I_{F(AV)}$	95 A
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MECHANICAL DESCRIPTION

The ADD-A-PAK Generation VII, new generation of ADD-A-PAK module, combines the excellent thermal performances obtained by the usage of exposed direct bonded copper substrate, with advanced compact simple package solution and simplified internal structure with minimized number of interfaces.

BENEFITS

- Excellent thermal performances obtained by the usage of exposed direct bonded copper substrate
- Up to 1600 V
- High surge capability
- Easy mounting on heatsink

ELECTRICAL DESCRIPTION

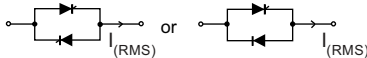
These modules are intended for general purpose high voltage applications such as high voltage regulated power supplies, lighting circuits, temperature and motor speed control circuits, UPS and battery charger.

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{T(AV)}$ or $I_{F(AV)}$	85 °C	95	A
$I_{O(RMS)}$	As AC switch	210	
I_{TSM} , I_{FSM}	50 Hz 60 Hz	2000 2094	
I^2t	50 Hz 60 Hz	20 18.26	kA ² s
$I^2\sqrt{t}$		200	kA ² √s
V_{RRM}	Range	400 to 1600	V
T_{Stg}		- 40 to 125	°C
T_J			

ELECTRICAL SPECIFICATIONS

VOLTAGE RATINGS					
TYPE NUMBER	VOLTAGE CODE	V _{RRM} , MAXIMUM REPETITIVE PEAK REVERSE VOLTAGE V	V _{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	V _{DRM} , MAXIMUM REPETITIVE PEAK OFF-STATE VOLTAGE, GATE OPEN CIRCUIT V	I _{RRM} , I _{DRM} AT 125 °C mA
VSK.91	04	400	500	400	15
	06	600	700	600	
	08	800	900	800	
	10	1000	1100	1000	
	12	1200	1300	1200	
	14	1400	1500	1400	
	16	1600	1700	1600	

ON-STATE CONDUCTION						
PARAMETER	SYMBOL	TEST CONDITIONS			VALUES	UNITS
Maximum average on-state current (thyristors)	I _{T(AV)}	180° conduction, half sine wave, T _C = 85 °C			95	A
Maximum average forward current (diodes)	I _{F(AV)}					
Maximum continuous RMS on-state current, as AC switch	I _{O(RMS)}				210	
Maximum peak, one-cycle non-repetitive on-state or forward current	I _{TSM} or I _{FSM}	t = 10 ms	No voltage reapplied	Sinusoidal half wave, initial T _J = T _J maximum	2000	
		t = 8.3 ms	No voltage reapplied		2094	
		t = 10 ms	100 % V _{RRM} reapplied		1682	
		t = 8.3 ms	100 % V _{RRM} reapplied		1760	
Maximum I ² t for fusing	I ² t	t = 10 ms	No voltage reapplied	Initial T _J = T _J maximum	20	kA ² s
		t = 8.3 ms	No voltage reapplied		18.26	
		t = 10 ms	100 % V _{RRM} reapplied		14.14	
		t = 8.3 ms	100 % V _{RRM} reapplied		12.91	
Maximum I ² √t for fusing	I ² √t (1)	t = 0.1 ms to 10 ms, no voltage reapplied T _J = T _J maximum			200	kA ² √s
Maximum value or threshold voltage	V _{T(TO)} (2)	Low level (3)	T _J = T _J maximum		0.97	V
		High level (4)			1.1	
Maximum value of on-state slope resistance	r _t (2)	Low level (3)	T _J = T _J maximum		2.76	mΩ
		High level (4)			2.38	
Maximum peak on-state or forward voltage	V _{TM}	I _{TM} = π × I _{T(AV)}	T _J = 25 °C		1.73	V
	V _{FM}	I _{FM} = π × I _{F(AV)}				
Maximum non-repetitive rate of rise of turned on current	di/dt	T _J = 25 °C, from 0.67 V _{DRM} , I _{TM} = π × I _{T(AV)} , I _g = 500 mA, t _r < 0.5 μs, t _p > 6 μs			150	A/μs
Maximum holding current	I _H	T _J = 25 °C, anode supply = 6 V, resistive load, gate open circuit			250	mA
Maximum latching current	I _L	T _J = 25 °C, anode supply = 6 V, resistive load			400	

Notes

(1) I²t for time t_x = I²√t × √t_x(2) Average power = V_{T(TO)} × I_{T(AV)} + r_t × (I_{T(RMS)})²(3) 16.7 % × π × I_{AV} < I < π × I_{AV}(4) I > π × I_{AV}



TRIGGERING					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum peak gate power	P _{GM}			12	W
Maximum average gate power	P _{G(AV)}			3.0	
Maximum peak gate current	I _{GM}			3.0	A
Maximum peak negative gate voltage	- V _{GM}			10	V
Maximum gate voltage required to trigger	V _{GT}	T _J = - 40 °C	Anode supply = 6 V resistive load	4.0	
		T _J = 25 °C		2.5	
		T _J = 125 °C		1.7	
Maximum gate current required to trigger	I _{GT}	T _J = - 40 °C	Anode supply = 6 V resistive load	270	mA
		T _J = 25 °C		150	
		T _J = 125 °C		80	
Maximum gate voltage that will not trigger	V _{GD}	T _J = 125 °C, rated V _{DRM} applied		0.25	V
Maximum gate current that will not trigger	I _{GD}	T _J = 125 °C, rated V _{DRM} applied		6	mA

BLOCKING				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum peak reverse and off-state leakage current at V_{RRM} , V_{DRM}	I_{RRM} , I_{DRM}	$T_J = 125\text{ }^{\circ}\text{C}$, gate open circuit	15	mA
RMS insulation voltage	V_{INS}	50 Hz, 1 s	3500	V
Maximum critical rate of rise of off-state voltage	dV/dt	$T_J = 125\text{ }^{\circ}\text{C}$, linear to 0.67 V_{DRM}	1000	V/ μ s

THERMAL AND MECHANICAL SPECIFICATIONS					
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS
Junction operating and storage temperature range		T _J , T _{Stg}		- 40 to 125	°C
Maximum internal thermal resistance, junction to case per leg		R _{thJC}	DC operation	0.22	°C/W
Typical thermal resistance, case to heatsink per module		R _{thCS}	Mounting surface flat, smooth and greased	0.1	
Mounting torque ± 10 %	to heatsink		A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow for the spread of the compound.	4	Nm
	busbar			3	
Approximate weight				75	g
				2.7	oz.
Case style			JEDEC	TO-240AA compatible	

ΔR CONDUCTION PER JUNCTION											
DEVICES	SINE HALF WAVE CONDUCTION					RECTANGULAR WAVE CONDUCTION					UNITS
	180°	120°	90°	60°	30°	180°	120°	90°	60°	30°	
VSK.91..	0.04	0.048	0.063	0.085	0.125	0.033	0.052	0.067	0.088	0.127	°C/W

Note

- Table shows the increment of thermal resistance R_{thJC} when devices operate at different conduction angles than DC

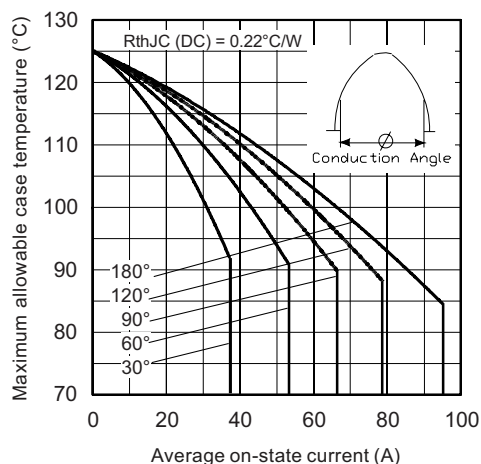


Fig. 1 - Current Ratings Characteristics

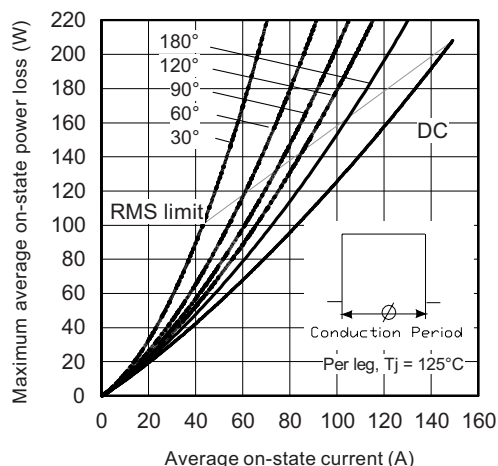


Fig. 4 - On-State Power Loss Characteristics

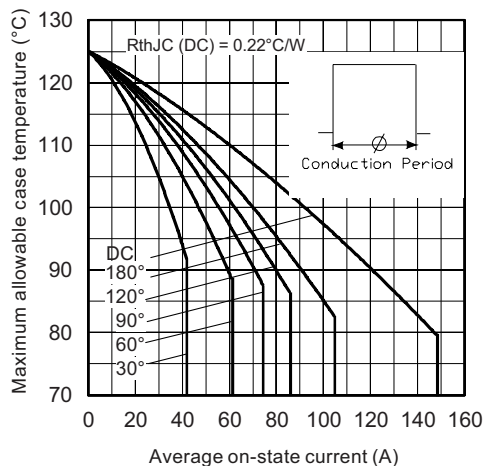


Fig. 2 - Current Ratings Characteristics

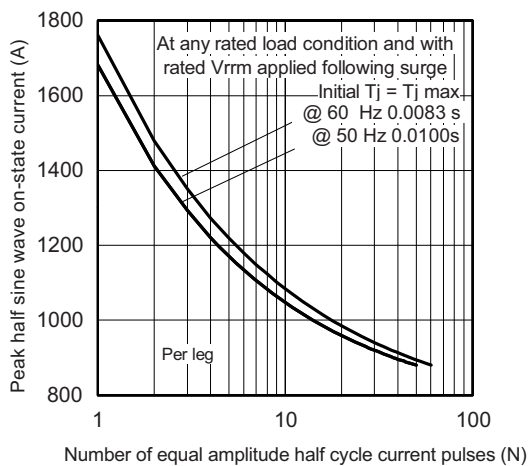


Fig. 5 - Maximum Non-Repetitive Surge Current

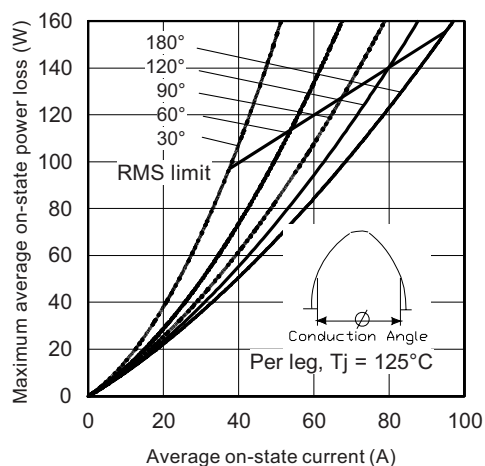


Fig. 3 - On-State Power Loss Characteristics

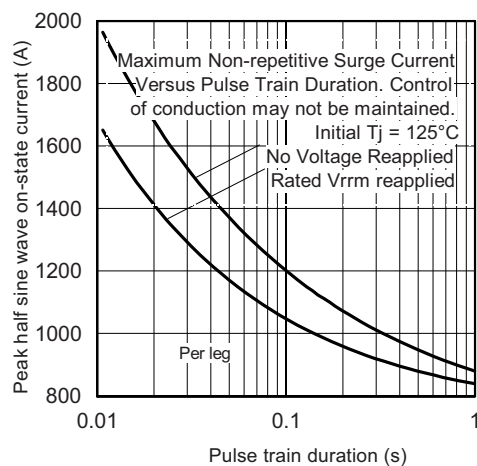


Fig. 6 - Maximum Non-Repetitive Surge Current

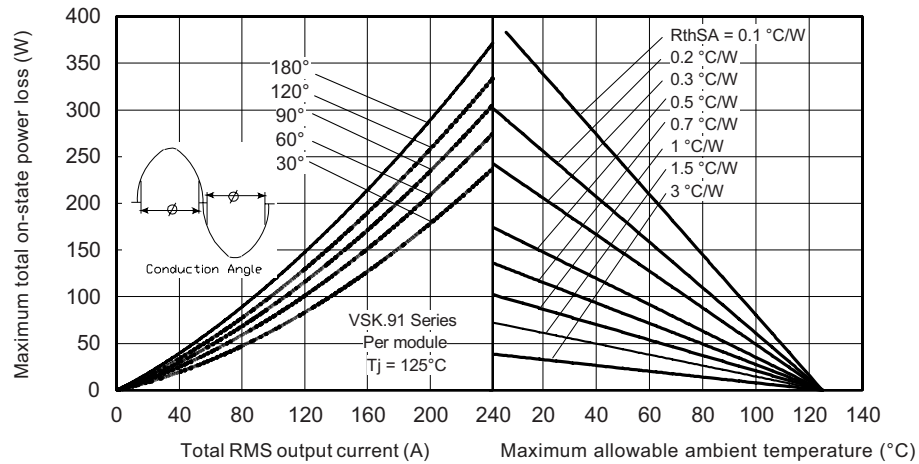


Fig. 7 - On-State Power Loss Characteristics

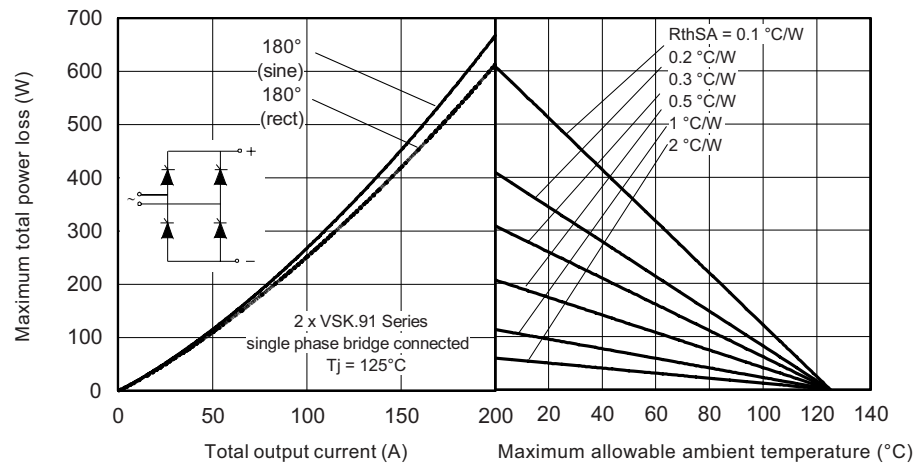


Fig. 8 - On-State Power Loss Characteristics

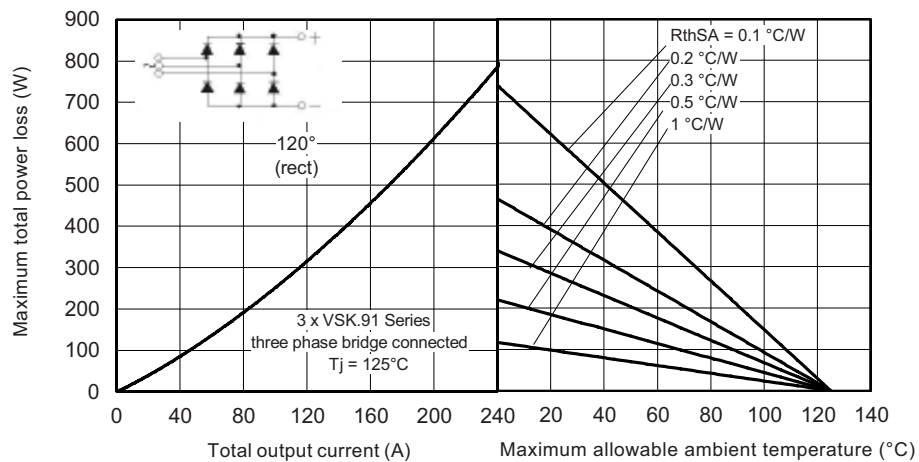


Fig. 9 - On-State Power Loss Characteristics

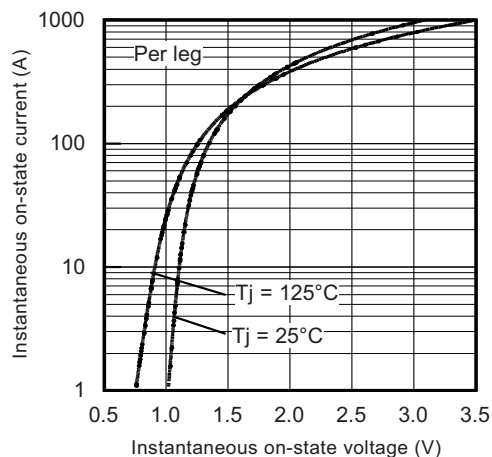


Fig. 10 - On-State Voltage Drop Characteristics

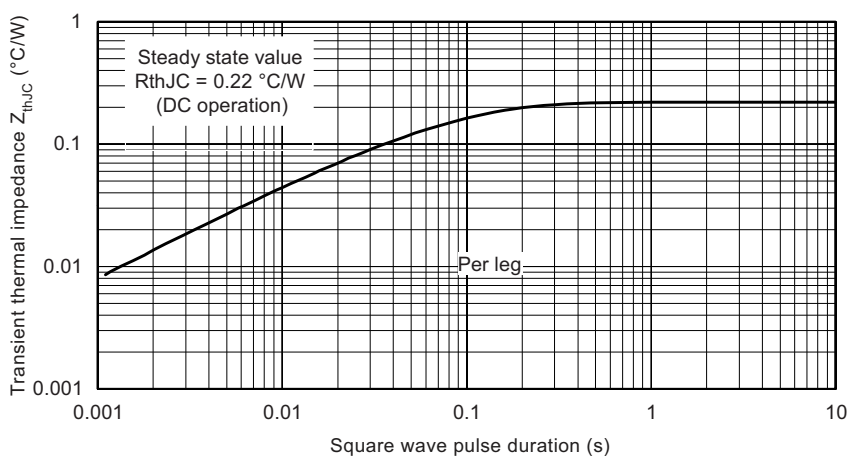


Fig. 11 - Thermal Impedance Z_{thJC} Characteristics

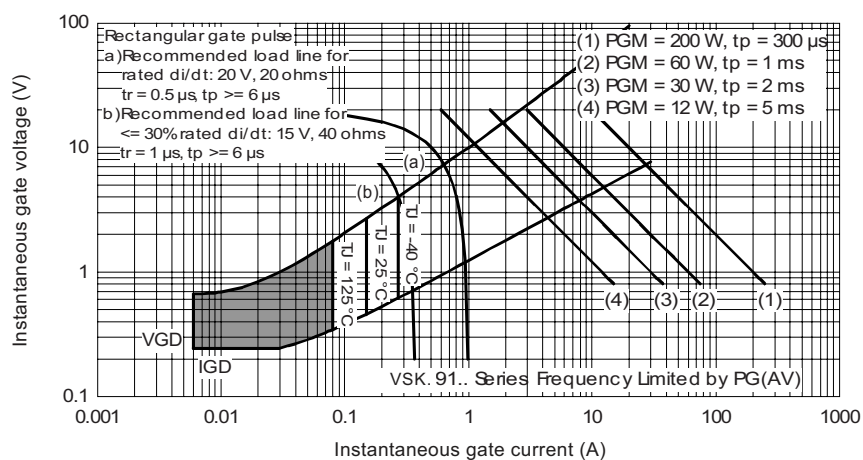
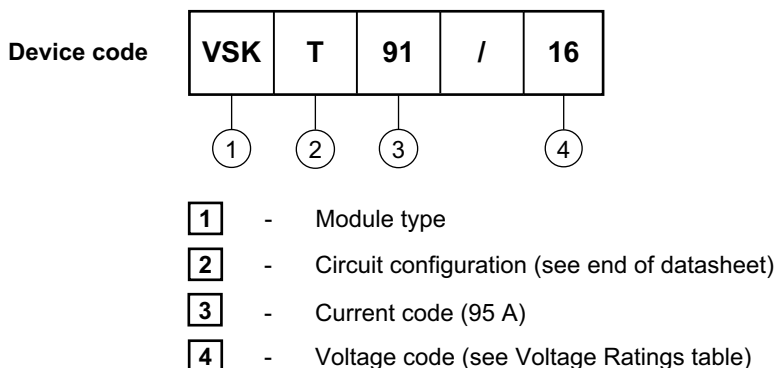
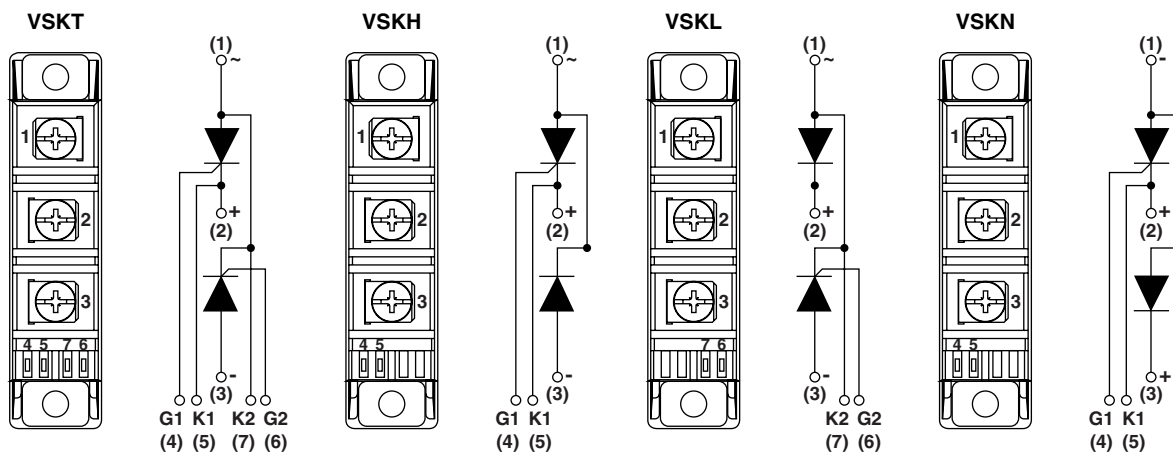


Fig. 12 - Gate Characteristics



- To order the optional hardware go to www.vishay.com/doc?95172



LINKS TO RELATED DOCUMENTS	
Dimensions	http://www.vishay.com/doc?95368



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Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9